

Full Wafer Test System

Single Wafer High Volume Production Test Solution



* Shown with a dual chuck probe,
dual FOUP loader and two
independent FOX-1P test systems

SYSTEM BENEFITS

- **Enables High Throughput, Single or Multi-Touchdown, Full Wafer Production Testing**
 - ◆ Capable of simultaneously testing thousands of die in a single wafer touchdown
 - ◆ Configurable channel resources per Blade (slot): Universal Channel Modules, High Voltage Channel Modules or High Current Channel Modules
 - ◆ Up to 16,384 “Universal Channel” resources: (I/O / Clock / PPMU / DPS) with deep scan, pattern data and capture memory per channel for test of devices with BIST/DFT
 - ◆ Software-enabled per site flexibility to support small and large device pin count test needs
- **Comprehensive functional and parametric test capabilities**
 - ◆ Deep functional pattern data and capture memory optimized for BIST/DFT testing
 - ◆ Per channel PMU for per site parametric testing
 - ◆ Individual channel over-current protection to protect wafers and probe cards
- **Configured for high volume production**
 - ◆ Compatible with industry standard probers and probe cards
 - ◆ Available as an integrated test cell with prober, probe cards and 16,384 channel probe card interface
 - ◆ Configurable as a single or dual system integrated test cell

“Setting the Test Standard for Tomorrow”

CORPORATE HEADQUARTERS

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